

Product/ Process Change Notification					
1. PCN No.:	QPCN13002				
2. Subject:	SMA rectifiers dimple shape-/dimension change				
3. To:	All customers who already ordered involved				
	products within the last 3 years				
4. Issued by:	Owen Wang				
5. Issue date:	28-Jan-2013				
6. Proposed first ship date for change:	29-Apr-2013				
7. Affected Product Identification					
See attached PCN/PDN involved P/N list.					
8. Change Description : (OLD Vs. NEW Co	mnarison)				
Old: New:					
See attached comparison report.	> See attached comparison report.				
9. Reason for Change:					
Dimple shape/dimension modification for solde	ering process optimization.				
10. Anticipated Impact: (form, fit, function, qu	ality or reliability)				
1. Product outline: No chai	nge				
2. Inner construction changed: Dimple construction change					
3. Electrical specifications: No change					
4. Reliability performance: No change					
5. Data sheet: No change					
6. Packing code (order code): No change					
7. Identification/Traceability: By date code					
11.Qualification plan/result:					
Refer to					
PPAP Available on					
Comparison report See attached					
12. Sample availability Date:	28-Jan-2013				
13. Tentative implementation date:	28-Jan-2013				
14. Remarks					
45 Customer feedback required latest	7 Max 2012				
15. Customer feedback required latest:	7-Mar-2013				
(should we receive no feedback; the change will be deemed as accepted!)					
16. Approved by:	Quayer Chen				
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Product/ Process Change Notification Customer Approval Form_QPCN13002

(Please tick the fleid what is valid for you!)						
	We agree with this proposed change and its schedule.					
	We have object	tions				
	We need more	information:				
	We need more	mormation.				
We need sample:						
Con	npany:					
Nan	ne:					
Add	Iress:					
Sigi	nature:		Date:			